

Title (en)

COMPONENT HAVING A CERAMIC BASE WITH A METALIZED SURFACE

Title (de)

BAUTEIL MIT EINEM KERAMISCHEN KÖRPER MIT METALLISIERTER OBERFLÄCHE

Title (fr)

COMPOSANT COMPRENANT UN CORPS CÉRAMIQUE QUI PRÉSENTE UNE SURFACE MÉTALLISÉE

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2008128945A1] It is difficult to dissipate the heat produced during the operation of components having flat metalized ceramic bases, especially if the ceramic bases are metalized on both surfaces. The component (1) according to the invention has a ceramic base (2) the surface (3, 4) of which is covered in at least one area by a metalized coating (5, 6), the ceramic base (2) being spatially structured (7).

IPC 8 full level

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CPC (source: EP KR US)

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